Product End-of-Life Disassembly Instructions

Product Category: Notebooks and Tablet PCs

Marketing Name / Model
[List multiple models if applicable.]

Star Wars™ Special Edition Notebook
Star Wars™ Special Edition Notebook 15

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm MB, USB board, Power board, TouchPad</td>
<td>4</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries Cell battery &amp; RTC Battery</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>

PSG instructions for this template are available at EL-MF877-01
Components, parts and materials containing radioactive substances | 0

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1</td>
<td>#1</td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove battery
2. Dis-fasten ODD screw *1
3. Disassemble ODD assembly
4. Dis-fasten bottom cap L&R screw*2
5. Disassemble bottom cap L&R
6. Dis-assemble Base screw mylar*2
7. Dis-fasten base screw*17
8. Dis-assemble base assembly
9. Dis-assemble RAM module
10. Pull out LCD cable & Antenna cable
11. Dis-fasten hinge screw*3
13. Pull out DC cable & speaker assembly
14. Dis-fasten Power board screw
15. Dis-assemble Power Board
16. Pull out HDD FFC
17. Disassemble HDD assembly
18. Dis-fasten Fan screw*2
19. Disassemble Fan module
20. Pull out USB board FFC & Power board FFC
21. Dis-fasten USB board screw*2
22. Dis-assemble USB board
23. Dis-fasten thermal module screw(DIS*6 ; UMA*4)
24. Dis-assemble thermal assembly
25. Pull out KB membrane & TP FFC
26. Dis-fasten MB screw*4
27. Dis-assemble MB assembly
28. Dis-assemble LCD screw mylar
29. Dis-fasten LCD screw*2
30. Dis-assemble LCD bezel assembly
31. Dis-fasten LCD panel screw*4
32. Dis-assemble LCD module
33. Pull Camera module and LCD cable from LCD module
34. Dis-fasten Hinge bracket screw*6
35. Remove Hinge L & R
36. Remove Antenna cable L & R

PSG instructions for this template are available at [EL-MF877-01](#).
3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

3.21 Total part disassembly

3.22 Remove battery module

3.23 Remove service door
3.24 LCD module set disassembly

3.25 Top case disassembly
3.26 Thermal module and mother board disassembly

3.27 Bottom case disassembly